# HERCROM400G2

# **Specification**

# CAL000

Ver 1.4

# CALYPSO

Department: European Wireless Terminal Chipset Business Unit

	Originator
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Date	25 - February- 2000

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PAGE: 1/54

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# HISTORY

#### Notes:

- 1. Creation of document.
- 2. Version derived from specification SAMS000 v1.7
- 3. Final ball-out assignment.
- 4. Change MPU adress.
- 5. Updated §4.5.14, §4.5.22, §4.5.23, §4.5.24, §4.9
- 6. Updated connection figures
- 7. Fix bug in MPU paragraph.
- 8. Fix bug for KBC, DATA, TSPEN reset values.
- 9. Updated section 11.3 : removed warning concerning GNA2 pin connexion.
- 10. Updated Table 6 INT4n, Update §11.3 (Ground name), remove §reference document, added restrication with NAUSICA usage
- 11. Update table 3 : Compatibility connection with Nausica, update Table 6 (remove pull up on nIBOOT)
- 12. Remove all wrong references document.
- 13. Add §10-Table8 : PAD I/O Buffer type, update §3.5.21 MPU (minimum granularity of 8 bytes), update §3.5.22 DU, update §3.5.24 WRB.
- 14. Remove Pin EN\_LMM\_PWR in Ch 8 table Power management (wrong reference), update FIG 4 (1.8V instead of 1.4V)
- 15. update IOTA to power split DBB supply connections (ch 11.2.1.1)
- 16. add features for C035 : pin 140 nCS4 : update Table 7&8, Update Ch 7.1(Memory interface using ADD(22), using CS4)



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- 17. Improve lisibility for modifications done in previous version (Ch 8, 9, 10)
- 18. remove blank chapter 11.1 (Example of mobile terminal appication), update IOTA to power split DBB supply connections figure (pin VLRTC=1.5v)
- 19. Remove reference to F# (F741xxx, F751xxx instead)



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PAGE: 3/54

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**TI- Proprietary Information –** 

PAGE: 4/54

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## **SUMMARY**

1.	GLOSS	ARY	
2.	GENER	AL DESCRIPTION	9
3.	BLOCK	SPECIFICATION	9
	3.1 INT	TRODUCTION	9
	3.2 AR	M MEGACELL (ARM7TDMIE)	11
	3.3 DS	P SUBCHIP (S28C128)	12
	3.4 CLG	OCK SQUARER CELL	12
	3.5 AR	M PERIPHERALS	12
	3.5.1	Memory Interface	
	3.5.2	Internal Static RAM	
	3.5.3	Internal Boot Memory	
	3.5.4	Die ID cell	
	3.5.5	Interrupt Handler (INTH).	
	3.5.6	General purposes I/O (ARMI/O)	
	3.5.7	Micro Wire interfaces (UWIRE).	
	3.5.8	Timers (TIMER)	14
	3.5.9	IrDA Universal Async Receiver/transmitter 16C750 (UART-IRDA)	14
	3.5.10	Universal Async Receiver/transmitter 16C750 (UART-MODEM)	
	3.5.11	Subscriber Identity Module Interface (SIM).	
	3.5.12	Serial Port Interface (SPI)	
	3.5.13	Time Processing Unit (TPU)	
	3.5.14	Time Serial Port (TSP)	
	3.5.15	Direct Memory Access controller (DMA)	
	3.5.16	Clock Management (CLKM)	
	3.5.17	Pulse Width Tones (PWT)	
	3.5.18	Pulse Width Light (PWL)	
	3.5.19	Light Pulse Generator (LPG)	
	3.5.20	I2C master serial interface (I2C)	
	3.5.21	Memory Protection Unit (MPU)	
	3.5.22	Debug Unit (DU)	
	3.5.23	GPRS Encryption Algorithm (GEA1-2)	
	3.5.24	Internal RAM write buffer (WRB)	
	3.5.25	Real Time Clock (RTC)	
	3.5.26	Ultra Low-Power Down controller (ULPD)	
	3.6 SPE	CIFIC POWER-SPLIT FOR RTC	
	3.7 DS	P PERIPHERALS	
	3.7.1	Radio interface (RIF)	
	3.7.2	Multi-Channel Serial Interface (MCSI)	,
	3.7.3	Ciphering processor (CRYPT)	,
	3.7.4	Universal Asynchronous Receiver/transmitter (16C750)	
	3.7.5	Direct Memory Access controller (DMA)	
	3./.0	Interrupt Handler (INIH).	
	3.8 GEI	NERAL PURPOSE PERIPHERALS	
	5.8.1		
	3.8.2		
	3.9 BL(		
4.	INITIA	LIZATION PROTOCOL	
	4.1 HA	RDWARE LOGIC RESET	23



**TI- Proprietary Information –** PAGE: 5/54

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#### REF: CAL000

#### HERCROM400G2

4.2	ARM CODE DOWNLOADING	
4.3 5. IN	VTERRUPTS MANAGEMENT	
5.1 5.2	DSP INTERRUPTS	25
6. DI	MA MAPPING	
7. Al	DDRESS MAPPING	
7.1	ARM MEMORY SPACE	
7.1	1.1 Memory interface: using CS4 (default)	
7.	1.2 Memory interface: using ADD(22)	
7.1	1.3 External Flash/ROM image	
7.2	DSP MEMORY SPACE	
7.2	2.1 API	
7.2	2.2 XIO-RHEA	
<b>8.</b> CA	ALYPSO PINS DESCRIPTION	
<b>9.</b> CA	ALYPSO BALL-OUT	
9.1	179GHH PACKAGE	
10.	PAD I/O BUFFER TYPE	
11.	APPLICATION EXAMPLE	
11.1	POWER-SUPPLIES CONNECTION	
11	1.1.1 Compatibility schematic Nausica CALYPSO	
11	1.1.2 IOTA to power split DBB supply connections	
11	1.1.3 Power Supplies connection with IOTA ABB	
11.2	32KHz QUARTZ CONNECTION	
11.3	SIM CARD CONNECTION	
114	KEYBOARD CONNECTION	54



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**TI- Proprietary Information –** 

PAGE: 6/54

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## **TABLE SUMMARY**

TABLE 1: RESET MANAGEMENT	. 24
TABLE 2: DMA CHANNELS ALLOCATION	. 27
TABLE 3: ARM MEMORY SPACE	. 31
TABLE 4: ARM DATA FORMAT	. 32
TABLE 5: DSP XIO MEMORY SPACE	. 34
TABLE 6: CALYPSO PINS DESCRIPTION	. 38
TABLE 7: CALYPSO BALL MAPPING	. 43
TABLE 8: I/O BUFFER TYPE IN 179 BALLS VERSION	. 47
TABLE 9: Keyboard scanning sequence	. 54

## **FIGURE SUMMARY**

FIGURE 1: CALYPSO INTERNAL ARCHITECTURE	. 23
FIGURE 3: COMPATIBILITY CONNECTION WITH NAUSICA	. 48
FIGURE 4: POWER SUPPLIES CONNECTION WITH IOTA ABB	. 51
FIGURE 5: SIM CARD CONNECTION	. 53
FIGURE 6. KEYBOARD CONNECTION	54



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**TI- Proprietary Information –** 

PAGE: 7/54

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## 1. GLOSSARY

APIF:	Arm Port InterFace.
BGA:	Ball Grid Array.
CLOCK M:	CLOCK Managment.
CPU:	Central Processor Unit
DAI:	Digital Audio Interface
DSP:	Digital Signal Processor.
FLASH:	Flash E2prom
GSM:	Global System for Mobile communications.
HPI:	Host Port Interface.
H/W:	HardWare.
INTH:	INTerrupt Handler.
ISO:	International Standards Organization
I/O:	Input / Output.
JTAG:	Joined Test Action Group
MxxLyy	Mega-module DSP with xx RAM and yy ROM.
LCD:	Liquid Cristal Display
LMM:	DSP Mega-Module
MCU:	Micro-Controller Unit.
MCSI:	Multi Channels Serial Interface
MEM INT:	MEMory INTerface.
P.C.:	Personal Computer
PMT:	Parallel Multiplexing Test.
PLL:	Phase Loop Lock
RIF:	Radio Interface Function.
RISC:	Reduced Instruction Set Computer
RAM:	Random Access Memory
ROM:	Read Only Memory
SIM:	Subscriber Identity Module.
S/W:	SoftWare.
TDMA:	Time Division Multiple Access.
TPU:	Time Processing Unit.
TQFP:	Thin Quad Flat Pack.
TSP:	Time Serial Port.
USART:	Universal Synchronous/Asynchronous Receiver Transmitter
USB:	Universal Serial Bus
RTC:	Real Time Clock
ULPD:	Ultra Low Power Device
BIST:	Built In Self Test
LPG:	Led Pulse Generator
PWL:	Pseudo-noise pulse Width Light modulator
PWT:	Pulse Width Tone generator
I2C:	Inter IC Control



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PAGE: 8/54

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# 2. GENERAL DESCRIPTION

CALYPSO is a chip implementing the digital base-band processes of a GSM/GPRS mobile phone. This chip combines a DSP sub-chip (LEAD2 CPU) with its program and data memories, a Micro-Controller core with emulation facilities (ARM7TDMIE), internal 8Kb of Boot ROM memory, 4M bit SRAM memory, a clock squarer cell, several compiled single-port or 2-ports RAM and CMOS gates.

The application of this circuit is the management of the GSM/GPRS base-band processes through the GSM layer 1, 2 and 3 protocols as described in the ETSI standard with a specific attention to the power consumption in both GSM dedicated and idle modes, and GPRS (class 12) capability.

The chip will fully support the GSM full-level test approval (FTA) for both Full-Rate, Enhanced Full-Rate and Half-Rate speech coding.

CALYPSO implements all features for the structural test of the logic (full-SCAN, BIST, PMT, JTAG boundary-SCAN).

## 3. BLOCK SPECIFICATION

## 3.1 INTRODUCTION

CALYPSO architecture is based on two processor cores ARM7 and LEAD2 using the generic TI RHEA bus standard as interface with their associated application peripherals. CALYPSO is composed from the following blocks:

- ARM7TDMIE
  - ARM7TDMI CPU core (32/16 bits RISC processor)
  - + ARM ice crusher for emulation purpose
- DSP subchip S28C128
  - LEAD2 DSP core with 28K words of RAM and 128K words of ROM
  - + API (8 Kw part of the 28K of RAM)
  - + SPI
  - + TIMER
- Clock Squarer analog cell.
- ARM peripherals:

•

- General purpose peripherals
  - ARM Memory Interface for external RAM, Flash or ROM
- RHEA bridge
- 4 Mbit Static RAM with write-buffer
- Memory Protection Unit (MPU)
- Debug Unit (DU)
- 64 Kbit of via2-ROM for internal boot.
- Die-ID cell (48 bits + 5 spare).
- Application peripherals
- ARM General purposes I/O with keyboard interface and two PWM
- modulation signals for light and buzzer with possible tones generation.
- Micro Wire interfaces for LCD and EEPROM.
- 3 Timers (generic, watchdog)
- UART 16C750 interface (UART\_IRDA) with
  - IRDA control capabilities (SIR)
  - Software flow control (UART mode).
  - hardware flow protocol (DCD, CTS/RTS)
- UART 16C750 interface (UART\_MODEM) with
  - hardware flow protocol (DCD, CTS/RTS)
  - autobaud function

#### TEXAS INSTRUMENTS

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PAGE: 9/54

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• SIM Interface.



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PAGE: 10/54

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- ARM interrupts Handler (INTH).
- GSM real-time sequencer (TPU).
- GSM real-time Serial Port (TSP).
- DMA controller (4 channels 2 ports)
- Real Time Clock (RTC)
- GSM Ultra Low-Power Device (ULPD)
- Clock generator & control with Digital Phase Locked Loop (CLKM)
- Programmable controller for Led pulse generation (LPG)
- Enhanced tone generator (PWT)
- Pseudo-noise modulator for light level control (PWL)
- Master I2C serial interface
- GPRS Encryption Algorithm module 1 & 2.
- ASIC DSP peripheral:
  - General purpose peripherals
  - RHEA bridge
  - Application peripherals
  - Radio interface (RIF).
  - Multi Channels Serial Interface (MCSI).
  - A51/A52 ciphering (CRYPT)
    - UART 16C750 interface (UART\_MODEM) with
      - hardware flow protocol (DCD, CTS/RTS)
      - autobaud function, local echo.
    - DMA controller (4 channels)
  - DSP interrupts Handler (INTH).
- OTHER ASIC peripherals.
  - JTAG TAP controller.

#### 3.2 ARM megacell (ARM7TDMIE)

The ARM7TDMI is a 32 bits RISC micro-controller core. This microprocessor work in 32 bits or 16 bit instructions and on 32, 16 or 8 bit data. The ARM7 architecture is based on reduced instruction set computer (RISC). Pipelining is employed so that all parts of the processing and memory systems can operate continuously. Typically, while one instruction is being executed, its successor is being decoded, and a third instruction is being fetched from memory. In CALYPSO chips family, ARM7 is intended to work in **'little endian'** mode only.

The CPU is associated with an emulation module called IceCrusher, which provides many debug functions:

- Single processor and multiprocessor debug.
- High level language and assembly debug (Run, Halt, Step...).
- Real Time (CPU continuously running) or Non real-time (CPU stopped) debugs options.
- Combined 32 and 16 bit mode for ARM processor.
- Endianess transparency.
- Unlimited breakpoints via op-code replacement (S/W breakpoint).
- 2 Hardware breakpoints (one configurable as SW breakpoint) with maskable cycle type, address and data compare.
- 2 external breakpoint events.
- Internal events generate external triggers.
- Benchmarking / profiling capability.



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PAGE: 11/54

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#### 3.3 DSP subchip (S28C128)

The DSP subchip is a Digital Signal Processor core compliant with the TMS320C54x family. The CPU core LEAD2 is associated with a ARM Port Interface (API), an interrupt handler, a parallel interface XIO, a Timer, 28K words of RAM including 8K words of API shared memory, 128K words of ROM, a serial port, and a JTAG interface.

The input clock frequency is delivered by an external DPLL and the functional cycle frequency is planned to be in the range [0 - 91 MHz].

#### 3.4 Clock Squarer cell

The Clock Squarer cell is an analog cell which function is to reshape a clock signal provided by an external oscillator. The input signal is assumed to be a pseudo-sinusoidal signal with a limited dynamic transformed by the Clock Squarer cell in a square waveform with an amplitude of VCC (see electrical characteristics of signal CLKIN in Appendix B).

#### 3.5 **ARM** peripherals

#### 3.5.1 *Memory Interface.*

The Arm memory interface handles:

- External ARM memory access management: It performs
  - ⇒ ARM read and write access size adaptation to the memory width (from 8-bit up to 32-bit).
  - ⇒ ARM access duration management (wait state insertion or using 'nREADY' input) to enable the connection of slow memory devices.
  - $\Rightarrow$  Memory control signals generation (chip-selects, write strobe generation,...) with up to 4 chip-select signals corresponding each to an address range of 8 Mbytes.
- ARM to API memory access management:
  - ⇒ ARM access size adaptation for API read and writes access. A 32-bit API READ transaction is transformed into 2 16-bit read access. A 32-bit API WRITE access is transformed into 2 16-bit write transaction.
  - $\Rightarrow$  Address signal-timing adaptation to be compliant with the API interface requirement.
- ARM to Rhea bridge access management:
  - ⇒ ARM accesses size adaptation for Rhea accesses. The access size adaptation is done regarding the Rhea peripheral minimal transaction size. If the Rhea peripheral can not handle byte transaction, then no byte write transaction can be done.
- ARM nWAIT and access control flags generation (byte-latch, etc...).

#### 3.5.2 Internal Static RAM

Four megabit of static RAM (SRAM) are embedded on the die and mapped on nCS6 chipselect of the memory interface. These memories can be read or written either in 8, 16 or 32 bits format. The access cycle is guaranteed with 0 wait-state for any cycle frequency up to fmax MHz.



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PAGE: 12/54

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#### 3.5.3 Internal Boot Memory

A 64Kbit ROM is embedded and mapped on nCS7 chip-select of the memory interface. This memory can be read either in 8, 16 or 32 bits format. The access cycle is guaranteed with 0 wait-state for any cycle frequency up to fmax MHz.

Depending of the state of the nIBOOT signal, this memory is mapped on nCS0 or nCS7, to allow the CPU to boot (at reset) on external or internal memory.

#### 3.5.4 Die ID cell

The Die ID cell is a 64-bit register composed of fuse cells programmed by Laser during fabrication process. Each Die ID is unique.

See chapter 16.4.

#### 3.5.5 Interrupt Handler (INTH).

The interrupt handler provides 21 prioritized and maskable interrupts to the ARM core.

It receives interrupts from both internal modules and external chip environment. Each incoming interrupt is configured as a low level sensitive or falling edge sensitive interrupt and can be individually masked using dedicated configuration registers.

An Interrupt Level Register is associated to each incoming interrupt to define a priority to the corresponding interrupt. If several interrupts have the same priority level, they are sent in a predefined order.

Each interrupt can be routed to one of the two input interrupts of the ARM core FIQ (Fast Interrupt request) and IRQ (Low priority Interrupt request).

#### 3.5.6 General purposes I/O (ARMI/O).

We provide fifteen I/O pins configurable in read or write mode by internal registers.

10 special I/O pins are dedicated for keyboard connection: 5 output (Columns) and 5 input (Rows). The five input pins are connected on 1 interruption for wake-up mode.

A Pulse Width Modulated pin is dedicated to the control of the buzzer. A dedicated timer is used to generate the waveform shape, which modulates the buzzer PWM signal thus producing tones in the human audible spectrum.

#### 3.5.7 Micro Wire interfaces (UWIRE).

only

This serial interface can drive external devices as serial EEPROM or LCD with 2 chip-selects with respect to the micro wire standard.

The serial clock period is derived from the reference 13MHz clock and can be configured as: T<sub>SCLK</sub> = CK\_FREQ \* Csi\_FRQ \* T<sub>13M</sub> = [2/4/7/10] \* [2/4/8] \* T<sub>13M</sub>

#### Note: the use of the uWIRE interface is exclusive with the use of the I2C interface (same I/O pins).



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PAGE: 13/54

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#### 3.5.8 Timers (TIMER).

The chip implements three 16 bits timers configurable either in 'auto reload' or in 'one shot' modes. The timers generate interrupts to the ARM when equal to zero.

The first timer is configured by default as a Watchdog for the MCU. If a programmer doesn't want to have this functionality, he must write a specific sequence into a dedicated register in order to configure it as a general-purpose timer.

The two other timers are general-purpose timers.

#### 3.5.9 IrDA Universal Async Receiver/transmitter 16C750 (UART-IRDA).

This UART interface is compatible with 16C750 compliant devices. It includes the Slow Infra Red protocol in order to be connected with an infrared transmitter to any external data peripherals with an IrDA compliant data interface.

The IR function can be disabled and the UART connected through a standard wired interface. This UART is primarily intended to be linked with the modem of an external PC for concurrent debugging purpose.

The module integrates two 64 words (9 and 11 bits) receive and transmit FIFO and one 8 words (8 bits) status FIFO (IrDA only) which trigger levels are programmable. The baud-rate is internally generated from a programmable divisor.

Transmission parity can be even, odd, none and the number of stop bits is 1, 1.5 or 2.

The receiver can detect break, idle or framing errors, and FIFO overflow and parity errors.

The transmitter can detect FIFO underflow.

All modem operations are controllable via a software interface.

In IrDA mode, this upgraded UART 16C750 includes the following additional features:

- IrDA 1.0 SIR support allows serial communication at baud rates up to 115.2 kbaud.
- Pulse shaping, and pulse recovering. Sending a single infrared pulse signals a zero. A one
  is signaled by not sending any pulse. The width of the pulse can be either 1.6 us or 3/16<sup>th</sup>
  of a single bit time.
- The device operation, in IrDA 1.0 SIR, is similar to the operation in UART mode. The main difference being that the data transfer operations are normally performed in half-duplex, the modem control and status signals are not used.
- Frame formatting: addition of variable xBOF characters and EOF characters
- Uplink/downlink CRC generation/detection
- Asynchronous transparency (automatic insertion of break character)
- 8 characters status FIFO available to monitor frames length and frame errors.
- Variable frame length for RX and TX IrDA frame.

only.

<u>Note</u>: MIR and FIR are not implemented.



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PAGE: 14/54

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#### 3.5.10 Universal Async Receiver/transmitter 16C750 (UART-MODEM)

This UART interface is compatible with the NS 16C750 device.

This UART 16C750 is devoted to the connection to a Modem through a standard wired interface.

The module integrates two 64 words (9 and 11 bits) receive and transmit FIFOs which trigger levels are programmable. The baud-rate is internally generated from a programmable divisor. Transmission parity can be even, odd, or none and the number of stop bits is either1, 1.5 or 2. The receiver can detect break, idle or framing errors, FIFO overflow and parity errors. The transmitter can detect FIFO underflow.

All modem operations are controllable either via a software interface or using hardware flow control signals.

This upgraded UART 16C750 includes the following additional features:

- Hardware flow control (DCD, RTS/CTS)
- Auto-bauding with the possibility to match to baud-rate from 1200 to 115.2Kbits/s.

This UART is shared between the ARM7 and the DSP processors. One processor only at a time can controlled the UART. The allocation of the UART is defined by the ARM7 (configuration register). By default, the UART is connected to the ARM7 RHEA bus.

#### 3.5.11 Subscriber Identity Module Interface (SIM).

The Subscriber Identity Module interface will be fully compliant with the GSM 11.11 and ISO/IEC 7816-3 standards.

Its external interface is 3 Volts only. 5 Volts adaptation will be based on external level shifters. The SIM interface supports the cold and warm reset procedures and the disabling of the clock (static SIM cards).

#### 3.5.12 Serial Port Interface (SPI)

The SPI is a full-duplex serial port configurable from 1 to 32 bits and provides 3 enable signals programmable either as positive or negative edge or level sensitive.

The serial clock period is derived from the reference 13MHz clock and can be configured as:  $T_{MCUCLK} = PTV * T_{13M} = [1/2/4/8/16] * T_{13M}$ 

#### 3.5.13 Time Processing Unit (TPU)

The TPU is a real-time sequencer dedicated to the monitoring of GSM base-band processing's. Working from an event table referring to a GSM TDMA time base, the TPU activates tasks to control DSP peripherals with respect of the time constraints related to the GSM sequencing. To store the real-time microinstructions of the sequencer, the TPU includes one 2 ports RAM of 1024 words of 16 bits with a dual page addressing capability.

MCU could access at the full RAM in write mode only when TPU is running.



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## 3.5.14 Time Serial Port (TSP)

The TSP is a peripheral of the TPU, which includes both a serial port (32 bits) and a parallel interface. The serial port can be programmed by the TPU with a time accuracy of the quarter of GSM bit. The serial port is uni-directional (transmit only) when used with NAUSICA but can be configured in bi-directional to keep compliant with VEGA3. The serial ports provide 4 enable signals programmable either as positive or negative edge or level sensitive.

The parallel interface allows controlling 13 external individual output and 1 internal signal with a time accuracy of the quarter of GSM bit.

These parallel output signals are mainly used to control the RF activity.

The single internal signal is looped on one interrupt line of the DSP in order to offer a possibility of sequencing the DSP tasks scheduling on a quarter of GSM bit time accurate event.

The serial clock frequency is fixed to 6.5MHz.

### 3.5.15 Direct Memory Access controller (DMA)

The DMA controller manages data transfers between the RHEA peripherals and the DSP API memory. The main features are:

- Four independent DMA channels
- Configuration of channels from the MCU only (master, direction)
- Either the DSP or the ARM host can control each DMA channel
- All DMA transactions are using the ARM Rhea bus
- The DMA transaction width can be either 8 or 16-bit data
- Unknown transfer length support and double-page destination buffers

#### 3.5.16 Clock Management (CLKM)

This module is in charge of the control of the clock activity for the DSP, MCU and RHEA peripherals. It includes one DPLL and configuration register for DSP and MCU clocks frequencies programming.

CLKM manages also the reset of all modules connected either to the MCU Rhea bus or the DSP Rhea bus and the scheduling of the deep power of the external FLASH memory.

The DPLL is programmable in "multiplication-mode" with the following values:

$$F_{out} = F_{in} \times \frac{m}{d}$$
 m = 1 up-to 32 (step 1) d = 1, 2, 3 or 4

It could be also programmable in "division-Mode" with the following:

$$F_{out} = \frac{F_{in}}{k} \qquad \qquad k = 1, 2 \text{ or } 4$$

#### 3.5.17 Pulse Width Tones (PWT)

This module generates a modulated frequency signal for the external buzzer. Frequency is programmable between 349Hz and 5276Hz with 12 half tone frequencies per octave. The volume is also programmable.



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TI- Proprietary Information –

PAGE: 16/54

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#### 3.5.18 Pulse Width Light (PWL)

This module allows the control of the backlight of LCD and keypad by employing a 4096bit random sequence. This voltage level control technique decreases the spectral power at the modulator harmonic frequencies. The block uses a switchable clock of 32kHz, independent of UPS.

#### 3.5.19 Light Pulse Generator (LPG)

This peripheral produces the signal for the blinking LED. Blink period and duration are programmable.

#### 3.5.20 I2C master serial interface (I2C)

The I2C is a half-duplex serial port using 2 lines (data and clock) for data transmission with software addressable external devices. The interface is compliant with the Philips standard. The main features of the interface are:

- single master only
- standard (100KHz) and the fast (400KHz) transmission modes
- support both burst write, single read and combined read modes
- transmit burst buffer of 16 words
- 3 bits programmable spike filtering logic
- error handling capability during I2C bus access

# <u>Note:</u> the use of the I2C interface is exclusive with the use of the uWIRE interface (same I/O pins).

#### 3.5.21 *Memory Protection Unit (MPU)*

Within a memory space, the MPU allows defining memory sub-regions, each having a separate Read/Write protection attribute; this permits for partitioning the memory space into program instruction, system data, user data, stack ...

The application program configures the MPU, which interfaces to the processor via the RHEA bus. The address bus directly issued from the processor is monitored providing a real-time position of the memory region accessed. When a protection breach attempt occurs, the memory control signals are affected, not selecting the memory, and the fault condition is indicated to the processor.

The MPU allows for controlling:

- Up to four programmable protected regions within a memory space of 512 Kbyte.
- A maximum protected size of 128 Kbyte for each region (512 Kbyte for 4 regions).
- A minimum granularity of 8 bytes.
- A privileged-code memory region.

For each region, memory mapped control registers define:

- Protected memory region base-address.
- Starting/ending addresses within the protected memory region.
- Protection mode (Non-User R/W, User Read-only, ROM, Privileged-region write... -see Protection Mode definition-) applied to the memory sub-region bounded by the starting/ending addresses.
- Out-of-protection (upper-bound) indication enabled/disabled.



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#### TI- Proprietary Information – PAGE

PAGE: 17/54

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The MPU generates:

- An illegal-access signal if the application program attempts a non-authorized access to a memory region (i.e. User write access to a region programmed for User Read-only accesses).
- An Out-of-protection signal when the application program attempts to read or write to a location within a memory region (defined by the base-address) and above the upper limit (end-address) of the protected sub-region. (helpful for stack overflow/under-flow monitoring).
- A MPU-fault signal which is the OR'ed combination of both Illegal-access and Outof-protection signals.
- A fault indication (Illegal-access and/or Out-of-protection) flagged into the MPU status register which is available to the processor for fault analyze.

#### 3.5.22 Debug Unit (DU)

The Debug Unit is a hardware resource intended to provide additional support to a software abort-handler. The DU provides *64* stages deep history table of the last memory accesses prior entering the abort mode, then permitting analysis of previous bus transaction's.

The DU is an autonomous function that does not need to be configured, hence, does not interfaces to a control bus such as RHEA. The DU is connected directly to the processor busses (Address & Control) from where it collects the data, and to the memory interface system where the saved history table can be read.

The Debug Unit offers the following:

- Sixty-four 32-bit words deep FIFO register file
- 26-bit Processor Address and 8 Processor control signals recorded (nM[1:0], MAS[1:0], nEXEC, nOPC, nMREQ, nRW)
- Continuous storage for every processor fetch (either instruction or data)
- Data record automatically frozen upon switch to abort mode
- Memory-like read access during abort operating mode
- Enable/disable control from input module pin (typically connected to a chipconfiguration register-bit).
- General purpose RAM when debug function is disabled.

#### 3.5.23 GPRS Encryption Algorithm (GEA1-2)

In GPRS mode, the data confidentiality is performed by a ciphering function (GPRS Encryption Algorithm). The ciphering is executed within the LLC upper layer. According to the option negotiated with the network the GEA mode 1 or mode 2 may be selected.

The purpose of the LLC is to convey information between the mobile station and the Serving GPRS Support Node. The procedures used are modeled upon the HDLC concepts. The LLC shall support both acknowledge and unacknowledged mode and implement a FCS according to the mode used.

The HW block provided support the computation of the FCS according to the LLC frame to send/received as well as the ciphering/deciphering GEA mode 1 and 2. These procedures are described in 01.61, 04.64 GSM recommendations and detailed in GSM MoU documents.

#### 3.5.24 Internal RAM write buffer (WRB)

The write buffer increases the speed of memory accesses, thanks to write pipe mechanism. (The idea is to allow a complete CPU cycle time for read access).

Texas Instruments	TI- Proprietary Information –	PAGE: 18/54
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#### 3.5.25 Real Time Clock (RTC)

The RTC block is an embedded Real Time Clock module, directly accessible from RHEA bus interface.

Its basic functions are:

- Time information (seconds/minutes/hours) coded in BCD
- Calendar Information (Day/Month/Year/ Day of the week) directly in BCD code up to year 2099
- Alarm function with interrupts generation based on a periodical (second/minute/hour/day) or a precise time event in the century (second accuracy).
- 30s time range correction
- 32KHz oscillator frequency gauging.

#### 3.5.26 Ultra Low-Power Down controller (ULPD)

The ULPD block is used for the DEEP SLEEP MODE management. It allows stopping the accurate 13MHz VTCXO during the discontinuous reception phases in GSM idle mode in order to save power consumption. Moreover, the ULPD sequencer is used to monitor the chip activity in terminal OFF mode, thus deriving the original GSM Deep Sleep mode concept to the whole terminal activity.

The main functions of the ULPD block are:

- gauging of the 32 kHz quartz based oscillator
- maintenance of GSM time during deep sleep mode with the minimum time accuracy to allow a burst demodulation at wake-up
- programmable timer to exit deep sleep mode
- delivery of the 13MHz master to the CLKM module
- switching between 13MHz and 32KHz
- generation of chip functional reset

#### 3.6 Specific power-split for RTC

To have a minimum of consumption in mobile equipment, only the active logic elements have to be supplied. This approach is possible by using Split Power.

It consists by the use of Tactical Cells to split the core power domain in two sub domains powered with different voltage supplies.

The separation between the core and the active domain is realized by Tactical cells and more precisely by Internal Level Shifters. The Internal Level Shifters (ILS) are library standard macrocells to interface two core domains with two different supplies.

When the core domain is unknown, these cells have a Power-Down signal, which allows to set the output of the ILS to 0 and to have any through current. So ILS are going to be placed on each wire between the active elements and the core.

The aim of the Split Power is to have a minimum of consumption in OFF state. For a mobile the only necessary element to supply in OFF is the RTC. So the tactical cells will be placed to isolate the RTC.

To use the Split Power, Calypso had to have pins VDDRTC, VDDSRTC, VSSRTC as specific power-supplies for both core and IOs.

The pin which are going to be suplied with specific power supplies are :

- ON/OFF (in)
- NRESPWRON (in)
- IT\_WAKEUP (out)
- CLK32K\_OUT (out)
- OSC32K\_IN (Xtal in)
- OSC32K\_OUT (Xtal out)

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PAGE: 19/54

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TI- Proprietary Information –

PAGE: 20/54

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### 3.7 DSP peripherals

#### 3.7.1 Radio interface (RIF)

The RIF (Radio Interface) Module is a buffered serial port derived from the BSP peripheral module of the defined for TMS320C5X

The external serial data transmission is supported by a full-duplex double buffered serial port interface.

The DSP exchanges data with the RIF through either its

-XIO interface for configuration data and radio data in word by word protocol or its

- API interface for radio data in DMA mode (buffered mode with data block transfer)

For each data transfer between DSP and RIF, an interrupt is sent to DSP (XIO mode) or a DMA request and an 'end-DMA' request is sent to ARM.

Transmit serial clock is either generated internally or externally. Receive serial clock is always generated externally.

The RIF uses an internal 13MHz clock to manage the auto-buffering function.

#### 3.7.2 Multi-Channel Serial Interface (MCSI)

The MCSI is a serial interface supporting both single and multi-channels (x16) communications. Words length, frame format, baud-rates are fully programmable. The interface can be additionally configured to support GSM DAI test mode with the possibility to synchronize DAI with the voice frame signal.

### 3.7.3 Ciphering processor (CRYPT)

The ciphering processor implements both A51 and A52 algorithms as defined in GSM Rec03.20 and detailed in GSM MoU documents.

#### 3.7.4 Universal Asynchronous Receiver/transmitter (16C750)

UART interface compatible with the NS 16C750 device.

This UART is shared between the ARM7 and the DSP processors. One processor only at a time can control the UART. The ARM7 configuration register defines the allocation of the UART). By default, the UART is connected to the ARM7 RHEA bus.

### 3.7.5 Direct Memory Access controller (DMA)

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The DMA module is shared between DSP and MCU processors. The DMA have only two port DSP-API memory and MCU-RHEA, so it allows RHEA peripheral to use DMA channel between us and the API memory.



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TI- Proprietary Information – P

PAGE: 21/54

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#### 3.7.6 Interrupt Handler (INTH).

The interrupt handler provides 21 interrupts to the DSP core.

It receives interrupts from both internal modules and external chip environment. Each incoming interrupt is configured as a low level sensitive or falling edge sensitive interrupt. The mask and the interruption level of the interrupts are configured in the DSP core itself.

#### 3.8 General purpose peripherals

#### 3.8.1 JTAG

The JTAG interface (TAP) of the chip can be selected either

1. to access the 2 processors on-chip emulators with a pseudo IEEE JTAG protocol for emulation purposes. A PC or workstation can be connected to the interface to set the biemulation mode with the ARM core linked to DSP core. The IceCrusher module supports the synchronization between the 2 cores.

#### Or

2. To dialog with an embedded TAP controller which instructions set support all the IEEE 1149 BSCAN modes, the programming of the chip I/Os configuration (PMT modes, full-scan modes, BIST modes, functional 1 or 2 modes) and the selection of the boundary-scan chain for FLASH EPROM programming.

#### 3.8.2 IDDQ

Pulling high the IDDQ pin sets the IDDQ configuration.

In IDDQ mode, all analog devices are disabled thus allowing reducing the chip current consumption to the single leakage currents. Moreover, a direct control of the ARM and DSP resets and clocks is allowed through, respectively, the pin BCLKR and CLKTCXO of the chip.



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PAGE: 22/54

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### 3.9 Block Diagram



Figure 1: CALYPSO internal architecture

# 4. INITIALIZATION PROTOCOL

#### 4.1 Hardware logic reset

The chip receives one external reset signal (active low):

\* The power-on reset (nRESPWRON) initializes the whole digital logic devices. It is activated each time the power supply is applied to the chip.

The functional reset is generated internally from the ULPD controller:

\* The internal functional reset (nRESET) initializes the logic devices working on any clocks derived from the 13MHz-clock reference or the processor strobes. This reset is activated each time the terminal is switched in OFF mode and maintained active as long as the external control pin ON\_nOFF is at low level.



Internally to the chip, three reset signals are provided in order to dissociate the reset of the logic working on the 32KHz or TCK clocks and the reset of the logic working on clocks derived from the reference clock 13MHz or the processors strobes. Namely:

- nRESET\_32K  $\Rightarrow$  JTAG, RTC and ULPD modules.
- nRESET\_DSP  $\Rightarrow$  all logic mapped on the DSP Rhea bus except 32KHz based logic
- nRESET\_MCU  $\Rightarrow$  all logic mapped on the MCU Rhea bus except 32KHz based logic

Externally to the chip, two reset signals can be controlled by the MCU to reset selectively external components and to control the deep power mode of external FLASH memories

- nRESET\_OUT  $\Rightarrow$  external components.
- FDP  $\Rightarrow$  FLASH deep power (reset delay controlled with CNTL\_ARM\_CLK (deep\_power).

	Reset signal						
Control	nRESET_32K	NRESET_DSP	nRESET_MCU	nRESET_OUT	FDP		
NRESPWRON	Yes	Yes	Yes	Yes	Yes		
NRESET	No	Yes	Yes	Yes	Yes		
RST_CMD watchdog	No	Yes	Yes	No	Yes		
CNTL_RST(DSP_reset)	No	Yes	No	No	No		
CNTL_RST(ext_reset)	No	No	No	Yes	No		

#### Table 1: Reset management

\* CNTL\_RST is a control register mapped in the MCU memory space

After ARM reset the ARM program counter point to 0000:0000 address. After DSP reset the DSP program counter point to 0000:FF80 address.

Each module implements in its control register a software-reset bit, which can be activated by its master processor. By default, these bits are set as soon as the processor reset (nRESET\_DSP or nRESET\_DSP) is activated.

#### 4.2 ARM code downloading

In debug mode, when external Ram is used to replace FLASH or ROM, the program code is downloaded thanks to JTAG facilities. Flash memory program is downloaded through the JTAG TAP using the dedicated boundary-scan chain.

ROM or EPROM devices must be programmed before assembly.

#### 4.3 DSP code execution

When releasing the DSP reset signal nRESET\_DSP, the DSP fetches the reset interrupt vector at address FF80h and begins the execution of the program code.



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PAGE: 24/54

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## 5. INTERRUPTS MANAGEMENT

#### 5.1 DSP INTERRUPTS

The DSP subchip owns 17 interrupt lines with 11 of which INT0n to INT10n are dedicated for external peripherals. These interrupts are mapped as follows:

- RSN - INT0n - - INT1n - INT2n	(level) (level) (level)	-> -> -> ->	reset (HW or SW) RIF receive interrupt RIF transmit interrupt UART interrupt 1. Error on receiver line. 2. Receive timeout. 3. Received character.
			<ol> <li>Character to transmit.</li> <li>Modem status change.</li> <li>Received XOFF / special character detected.</li> <li>CTS/RTS deactivation.</li> </ol>
- TINT		->	Timer interrupts
- RINT		->	SPI receive interrupt
- RINT		->	SPI transmit interrupt
- INT3n	(level)	->	MCSI receive interrupt
- INT4n	(level)	->	MCSI transmit interrupt
- INT5n	(level)	->	MCSI frame duration error interrupt
- INT6n	(level)	->	MCSI DAI interrupt
- INT7n	(edge)	->	CYPHER interrupts <ol> <li>end of ciphering process</li> <li>error of processing</li> </ol>
- INT8n	(edge)	->	TPU frame interrupt
- AINT	、 <b>U</b> /	->	API interrupts
- INT9n	(edge)	->	TPU programmable interrupt
- INT10n	(level)	->	DMA interrupt
- nMIN	. ,	->	Abort on Rhea bus OR INT4n redirection

<u>Note:</u> The TPU programmable interrupt (INT9n) is a facility offered to the DSP programmer in order to allow the generation of a DSP interrupt at a dedicated time with a quarter of GSM bit accuracy. The interrupt is set in a scenario by using a time-stamped instruction.



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PAGE: 25/54

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#### 5.2 MCU INTERRUPTS

The ARM7 owns 2 interrupt lines nIRQ and nFIQ. The NAUSICA fast interrupt is mapped on nFIQ

All other peripheral interrupts are mapped on nIRQ as follows:

Name	Sense	IRQ	FIQ	Function		
IRQ0	edge	~		Watchdog TIMER interrupts		
IRQ1	edge	~		TIMER1 interrupt		
IRQ2	edge	~		TIMER2 interrupt		
IRQ3			~	TSP receives interrupt		
IRQ4	edge	~		TPU frame interrupt		
IRQ5	edge	~		TPU page interrupt		
IRQ6	edge	~		SIM interrupt		
				1. no answer to reset		
				2. character underflow		
				3. character overflow		
				4. character to transmit		
				5. received character		
				6. SIM card insertion/extraction		
IRQ7	level	~		UARI_MODEM interrupts		
				1. error on receiver line		
				2. receive timeout		
				3. received character		
				4. character to transmit		
				5. modem status change		
				7. CTS/DTS deactivation		
				CIS/RIS deactivation     CIS/RIS deactivation     (OFF made only)		
				Keyboard or logDial interrupt		
	edne	V 1		RTC periodical timer interrupt		
IRQ10	level	v ./		RTC ALARM or I2C data transfer error / completion		
IRO11	edge	~		III PD end of gauging interrunt		
IRQ12	level	~		External interrupt		
IRQ12	edge	· ·		SPL interrupt		
integro	cuge	•		1 received data		
				2. data to transmit		
IRQ14	level	~		DMA interrupt		
IRQ15	edge	~		API interrupts (nHINT)		
IRQ16	Ŭ		~	SIM card-detect fast interrupt		
IRQ17			~	Fast external interrupt		
IRQ18	level	~		UART IRDA interrupts		
		-		1. error on receiver line		
				2. receive timeout		
				3. received character		
				4. character to transmit		
				5. modem status change		
				6. Received XOFF / special character detected		
				7. CTS/RTS deactivation		
IRQ19	level	~		ULPD GSM timer		
IRQ20	level	~		GEA interrupt		



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PAGE: 26/54

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## 6. DMA MAPPING

The DMA controller is managing the access to the DSP API 6K-word shared memory.

- 1. The MCU ARM7.
- 2. The Radio InterFace (RIF).
- 3. The MODEM UART.
- 4. The IRDA UART.

The RIF-RX and RIF-TX have a dedicated channel each. For UART the following combination are possible:

- ⇒ UART-MODEM have 2 channels:
  - ch#2: TX
  - ch#3: RX
- $\Rightarrow$  UART-IRDA have 2 channels:
  - ch#2: RX
  - ch#3: TX
- ⇒ UART-MODEM and UART-IRDA have one channel each
  - ch#2: UART-MODEM
  - ch#3: UART-IRDA

RX and/or TX are independently selectable for each module.

- ⇒ UART-MODEM have one channel
  - ch#2: RX or TX

⇒ UART-IRDA have one channel

- ch#3: RX or TX
- $\Rightarrow$  UARTs have no DMA.

After reset, all modules have DMA functions disabled.

DMA request		cha	nnel	
DWATequest	0	1	2	3
RIF_DMA_REQ_X	~			
RIF_DMA_REQ_R		~		
nDMA_REQ_ARM(0) MODEM			~	
nDMA_REQ_ARM(1) MODEM				~
nDMA_REQ_ARM(0) IRDA				~
nDMA_REQ_ARM(1) IRDA			~	

Table 2: DMA channels allocation

<u>Note:</u> Only one UART at a time should be allocated to one DMA channel (2 or 3). The potential conflicts between concurrent DMA requests MUST be solved at system level with only one peripheral configured in DMA mode.

Texas Instruments	TI- Proprietary Information –	PAGE: 27/54
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# 7. ADDRESS MAPPING

#### 7.1 ARM MEMORY SPACE

ARM memory space is shared between external Memory Interface and RHEA bus. The Memory Interface is providing 6 chip-select signals.

All internal peripherals are mapped on ARM memory space with a range of 32Kbytes.

### 7.1.1 Memory interface: using CS4 (default)

#### Important : nCS4 is only available from Calypso C035 – F751xxx

(*): External memory					
Device name	nIBOOT	Start address	Stop address	Size (byte)	Data
	1	0000:0000	003F:FFFF	4M	9/16/22
10.50 ( )	0	0000:2000	003F:FFFF	4M – 8K	0/10/32
nCS6	-	0080:0000	00BF:FFFF	512K	8/16/32
not allocated	-	00C0:0000	00FF:FFFF	-	-
nCS1 (*)	-	0100:0000	013F:FFFF	4M	8/16/32
nCS2 (*)	-	0180:0000	01BF:FFFF	4M	8/16/32
nCS3 (*)	-	0200:0000	023F:FFFF	4M	8/16/32
CS4 (*)	-	0280:0000	02BF:FFFF	4M	8/16/32
nCS4 (*)	-	0280:0000	02BF:FFFF	4M	8/16/32
nCS0 image	-	0300:0000	033F:FFFF	4M	8/16/32
nC 97	1	0380:0000	03BF:FFFF	4M	9/16/22
11037	0	0000:0000	0000:1FFF	8K	0/10/32
Debug Unit (DU)	-	03C0:0000	03FF:FFFF	32	32
not allocated	-	0400:0000	FFCF:FFFF	-	-
API RAM	-	FFD0:0000	FFD0:3FFF	16K	16/32
API control register	-	FFE0:0000	FFE0:0001	2	16

## 7.1.2 Memory interface: using ADD(22)

#### Important : nCS4 is only available from Calypso C035 – F751xxx

(*): External memory					
Device name	nIBOOT	Start address	Stop address	Size (byte)	Data
nCS0 (*)	1	0000:0000	007F:FFFF	8M	9/16/32
	0	0000:2000	007F:FFFF	8M – 8K	0/10/52
nCS6	-	0080:0000	00BF:FFFF	512K	8/16/32
not allocated	-	00C0:0000	00FF:FFFF	-	-
nCS1 (*)	-	0100:0000	017F:FFFF	8M	8/16/32
nCS2 (*)	-	0180:0000	01FF:FFFF	8M	8/16/32
nCS3 (*)	-	0200:0000	027F:FFFF	8M	8/16/32
nCS4 (*)	-	0280:0000	02BF:FFFF	8M	8/16/32
nCS0 image	-	0300:0000	037F:FFFF	8M	8/16/32
nC97	1	0380:0000	03FF:FFFF	8M	9/16/32
11037	0	0000:0000	0000:1FFF	8K	0/10/32
Debug Unit (DU)	-	03C0:0000	03FF:FFFF	32	32
not allocated	-	0400:0000	FFCF:FFFF	-	-
API RAM	-	FFD0:0000	FFD0:3FFF	16K	16/32
API control register	-	FFE0:0000	FFE0:0001	2	16



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PAGE: 28/54

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Debug Unit	-		

## 7.1.3 External Flash/ROM image

In all case and whatever the value of the nIBOOT signal, the external memory mapped on nCS0 is accessible at address defined in nCS0-image range.



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PAGE: 29/54

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#### **RHEA** peripherals

Strobe 0 Device name		Start address	Ston address	Size in hytes	Data
reserved		EEE:0000		oize in bytes	Data
TDLL registers	<u> </u>	FEE:1000		116	16
reserved	0.02	EEE:1400	EEE:AEEE		10
	CS10	FEE:5000	FEEE:57EE	2K	- 8
UART MODEM	CS10	FEE:5800	FFFE:5FFF	21	8
UART MODEM	CS12	FEE:6000	FFFF:67FF	21	8
	0012	FEE:6800	FEEE.6EEE	21	-
RIF	CS14	FEE:7000	FFFF:77FF	2K	- 16
reserved	0014	EEE:7800	EEE:07EE	21	10
	CS18	FEE: 0000	FEEE.07EE	214	16
	CS10	FEEE-0800	FFFF:0801	21	16
configuration	0013	1111.3000	1111.3001	2	10
not allocated		FFFF:9802	FFFF·F7FF	_	_
GEA	CS24	EFEE:C000	EFEE:C7EE	2K	8/16
not allocated		FFFF:C800	FFFE·F7FF	21	-
Watchdog timer	CS31	FFFF:F800	FFFF:F8FF	256	16
	0001	FFFF:F900	FFFF:F9FF	256	16
		FFFF:FA00	FFFF:FAFF	256	16
Memory Interface		EEEE.EB00		256	16
		EEE.EC00		256	10
				250	10
				250	10
				256	10
Strobe 1 Device	lama	Start address	Stop address	200 Size in bytee	Data
SIM					<b>Dala</b>
	CS1	FFFE.0000		21	10
reconved	031	FFFE.0000		21	10
		FFFE.1000		- 2K	-
	CS4	FFFE. 1000		21	16
	CS4	FFFE.2000		21	10
120 SDI	035	FFFE.2000		21	16
	C30 C97	FFFE.3000		21	10
	CS8	FFFE.3000	FFFE.JFFF	2K	10
	C30	FFFE.4000 EEEE:4800		21	10
ARMIO	039	FFFE:4000		21	10
		FFFE.3000		-	- 16
TIVIENZ reserved	0313	FFFE.0000		21	10
	 CS15	FFFE.7000		- 2K	-
	CS15	FFFE.7000		21	0 9
	CS10 CS17	FFFE.0000		21	0 9
reconved	0317	FFFE.0000		21	0
	 	FFFE.9000	FFFE.EFFF	-	-
DSP configuration	0330		FFFE.F005	4	16
			FFFE.F003	2	10
Acia configuration				2	10
				2	10
Oco22K config	-			2	10
MCLL on the config	-			2	10
	-			<u>∠</u>	10
	0004			ð	01
reserved	0331	FFFE:F800	FFFE:FFFF	-	-



**TI- Proprietary Information –** 

PAGE: 30/54

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#### Table 3: ARM memory space



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PAGE: 31/54

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D32> D24 D23> D16	D15>D8	D7> D0	
nC	S0		
nC	S1		
nC	S2		
nC	S3		
C	S4		
nC	S6		
nC	S7		
API	RAM		
	М	PU	
	G	EA	
	AF	PIC	
	S	IM	
	T;	SP	
	TPU_	_REG	
	TPU_RAM		
	NOT MAPPED	RTC	
	UL	.PD	
	NOT MAPPED	I2C	
	S	PI	
	TIMER1		
	NOT MAPPED	LPG	
NOT MAPPED		PWL	
	Res	erved	
	NOT MAPPED	PWT	
	UWIRE		
	AR	MIO	
	NOT MAPPED	UART_IRDA	
		UART_MODEM	
	TIM	ER2	
	RHEA	bridge	
	IN	TH	
	Memory	Interface	
	DMA c	ontroller	
	CL	KM	
	JTAG	ID code	
	Die IE	) code	

Table 4: ARM data format



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PAGE: 32/54

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#### 7.2 DSP MEMORY SPACE

- 1. Provides 8K of API RAM starting at 0800h
- 2. RAM in a minimum system would be 8K.

	Data	Prog0	Prog1	Prog2	Prog3			
0000	Γ	DARAM overlay over the program area - 2K						
0800								
1000		API overlay over the program area						
1800		8K						
2000								
2800								
3000								
3800								
4000			orlow over the					
4800		DARAIVI OV	18k	e program are	a			
5000		IQV						
5800								
6000								
6800								
7000			-					
7800								
8000					55.014			
8800					PROM			
9000					86			
9800		PROM						
A000		28K						
A800	DROM		PROM	PROM				
B000	20K		32K	32K				
B800								
C000								
0000								
D000								
D800								
E000	וחס							
E000	ים יי ג	SK						
F000		/1 \						
F800								

### 7.2.1 API

The API interface offers a dual access capability to 8 kWords of 16 bits of mixed data program memory, it can be configured to manage data access of 8,16 or 32 bits through the API control registers and the memory interface configuration registers (See document [7]).

The API dual access capability is either enabled (SAM mode) or disabled (HOM mode) by the DSP. SAM mode is the default configuration when the DSP exits from a reset phase.

In SAM mode (Shared Access Mode), ARM (or DMA controller) and DSP can both access simultaneously to this shared memory space with ARM access resynchronized on DSP cycle-clock (3 times ratio required between ARM and DSP cycle clocks).

In HOM mode (Host Only Mode), the API RAM is dedicated to external access under the control of either the ARM or the DMA controller and therefore the access time is limited by the maximum access time of the used DARAM.

Texas Instruments	TI- Proprietary Information –	PAGE: 33/54
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## 7.2.2 XIO-RHEA

Internal and external peripherals are mapped on XIO or data memory spaces. Theses spaces are accessible through nXSTROBE[3:0] with a range of 2Kbytes for external peripherals allowing to connect up to :

- 6 external devices on program space
- 26 external devices on data space
- 31 external devices on I/O space
- internals peripherals are connected on I/O space or data memory space

DSP XIO-RHEA mapping.						
Device name		Start address	Stop address	Size in bytes	Data	
External periphera	als mappi	ng - Program spa	ace			
Strobe 0						
not allocated	CS0	0000	07FF	2K	16	
not allocated	CS5	3000	37FF	2K	16	
External periphera	als mappi	ng - Data Space	1			
Strobe 1						
not allocated	CS6	3800	3FFF	2K	16	
not allocated	CS15	7800	7FFF	2K	16	
External periphera	als mappi	ng - Data Space	2			
Strobe 2						
UART_MODEM	CS16	8000	87FF	2K	8	
not allocated	CS17	8800	8FFF	2K	16	
not allocated	CS31	F800	FFFF	2K	16	
External periphera	als mappi	ng -I/O Space				
Strobe 3						
RIF	CS0	0000	07FF	2K	16	
MCSI	CS1	0800	0FFF	2K	16	
not allocated	CS2	1000	17FF	2K	16	
not allocated	CS3	1800	1FFF	2K	16	
not allocated	CS4	2000	27FF	2K	16	
CYPHER	CS5	2800	2FFF	2K	16	
not allocated	CS30	F000	F7FF	2K	16	
XI0-2-RHEA	CS31	F800	F8FF	256	16	
bridge						
API Control		F900	F9FF	256	16	
INTH		FA00	FAFF	256	16	
not allocated		FB00	FBFF	256		
DMA controller		FC00	FCFF	256	16	
not allocated		FD00	FDFF	256		
not allocated		FE00	FEFF	256		
not allocated		FF00	FFFF	256		

Table 5: DSP XIO memory space



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PAGE: 34/54

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#### 8. **CALYPSO PINS DESCRIPTION**

MICRO_WIRE INTERFACE : 5 pins.		Pull	Reset	
SDI	IN	Data in.	LPU	input
SDO	OUT	Data out.		0
SCLK	OUT	Serial clock.		0
nSCS0	OUT	chip select 0.		1
nSCS1	OUT	chip select 1.		1

<b>UART16C750 IN</b>	Pull	Reset		
TXIR_IRDA	OUT	Infra-Red transmit pulse.		0
TX_IRDA	OUT	Transmit Data		1
RXIR_IRDA	IN	Infra-Red receive pulse.		Input
RX_IRDA	IN	Receive Data.		Input
SD_IRDA	OUT	IRDA transceiver ShutDown mode.		1

<b>UART16C750 IN</b>	UART16C750 INTERFACE (UART_MODEM): 5 pins.			Reset
TX_MODEM	OUT	Transmit Data.		1
RX_MODEM	IN	Receive Data.		Input
CTS_MODEM	IN	Clear To Send.		Input
RTS_MODEM	OUT	Request To Send.		1
DSR_MODEM	IN	Data Set Ready.		Input

GENERIC I/O PORT : 16 pins.			Pull	Reset
BU	OUT	Buzzer output with PWM.		0
LT	OUT	Light output with PWM.		0
IO(3:0)	IN/OUT	generic Input/Output.		input
KBC(4:0)	OUT	Keyboard matrix 5 by 5 column access.		11111
KBR(4:0)	IN	Keyboard matrix 5 by 5 row access.	PU	input

ARM MEMORY	NTERFAC	E: 49 pins.	Pull	Reset
ADD(21:0)	OUT	ARM address bus out		00000
DATA(15:0)	IN/OUT	ARM data bus		Output
nCS(3:0)	OUT	4 chip select active low.		1111
CS4	OUT	1 chip-select active high		0
RnW	OUT	RAM/FLASH memory read no write signal.		1
nBHE	OUT	Ext RAM1/RAM2 chip select .		0
nBLE	OUT	Ext RAM1/RAM2 chip select.		0
nFOE	OUT	Flash output enable for standby mode		1
nFWE	OUT	VPP command for flash write.		1
FDP	OUT	Flash deep low-power		0

Important: From Calypso C035 - F751xxx: Replace line above by				
nCS(4:0)	OUT	5 chip select active low.	11111	



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PAGE: 35/54

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#### HERCROM400G2

Ver 1.4

<b>TPU PARALLEL</b>	TPU PARALLEL PORT : 12 pins.			Reset
TSPACT(11:0)	OUT	Synchronous activation signal (GSM qbit)		H0000

TPU SERIAL PC	TPU SERIAL PORT : 7 pins.			Reset
TSPDO	OUT	Output serial data.		0
TSPDI	IN	Input serial data (VEGA3 compatibility only)		input
TSPEN(3)	OUT	Configurable triggers (edge/level)		1
TSPEN(2)	OUT	Configurable triggers (edge/level)		0
TSPEN(1:0)	OUT	Configurable triggers (edge/level)		11
TSPCLKX	OUT	Transfer serial clock (VEGA3 compatible)		0

ARM SERIAL PO	ARM SERIAL PORT : 5 pins.			Reset
MCUDI	IN	Input serial data.		input
MCUDO	OUT	Output serial data.		0
MCUEN(2:0)	OUT	Configurable enable triggers (edge/level)		111

JTAG PORT : 7 pins.			Pull	Reset
TDI	IN	Test Data Input.	LPU	Input
TDO	OUT	Test Data Output.		Z
TMS	IN	Test Mode Select.	LPU	Input
TCK	IN	Test Clock.	LPD	Input
nEMU0	IN/OUT	Test Emulation pin 0.	PU	Input
nEMU1	IN/OUT	Test Emulation pin 1.	PU	Input
NBSCAN	IN	Boundary-scan selection	PU	1

MISCELLANEO	MISCELLANEOUS : 11 pins.			Reset
CLKTCXO	IN	VCTXO input clock (13MHz or 26MHz).		Input
CLK13M_OUT	OUT	CLKM output clock (13MHz).		0
OSC32K_IN	IN	Input component signal of 32KHz quartz.		Input
OSC32K_OUT	IN	Output component signal of 32KHz quartz.		Input
CLK32K_OUT	OUT	32KHz oscillator square waveform output		0
NRESPWRON	IN	Chip Power-On reset		0
nRESET_OUT	OUT	Reset of external peripherals.		0
EXT_IRQ	IN	External interrupt for ARM	PU	Input
EXT_FIQ	IN	Fast external interrupt for ARM	PU	Input
IDDQ	IN	Static config. in IDDQ mode (active high)		Input
nIBOOT	IN	Internal/External Boot memory		Input

POWER MANAG	EMENT : 5	pins.	Pull	Reset
IT_WAKEUP OUT Wake-up interrupt of Real Time Clock.				0
TCXOEN	OUT	External TCXO enable		0
RFEN	OUT	External RF IC enable		0
ON_OFF	IN	Regulators activity		Input

VOICE BAND IN	TERFACE	: 4 pins.	Pull	Reset
VCLKRX IN Transmit/Receive clock.				Input
VDX	OUT	Transmit Data.		0
VDR	IN	Receive data.		Input
VFSRX	IN	Transmit/Receive Synchro.		Input



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## **TI- Proprietary Information –**

PAGE: 36/54

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MCSI INTERFACE : 4 pins.			Pull	Reset
MCSI_TXD	OUT	Transmit serial data		0
MCSI_RXD	IN	Receive serial data		Input
MCSI_CLK	IN/OUT	Bit synchronization clock		Input
MCSI_FSYNCH	IN/OUT	Frame synchronization clock or SS reset		Input

BASE BAND INT	Pull	Reset		
BFSR	IN	Receive synchro.		Input
BDR	IN	Receive data.		Input
BFSX	OUT	Transmit synchro.		0
BDX	OUT	Transmit data.		0
BCLKR	IN	Receive serial clock (VEGA3 compatibility)		Input
BCLKX	IN/OUT	Transmit serial clock (VEGA3 compatibility)		Input

SIM INTERFACE	: 6 pins.		Pull	Reset
SIM_RST	OUT	Sim reset.		0
SIM_PWCTRL	OUT	Power Control.		0
SIM_IO	IN/OUT	Input output signal.		0
SIM_CLK	OUT	Output clock.		0
SIM_CD	IN	Card detect (VEGA3 compatibility)		Input
SIM RnW	OUT	Direction of IO data line		0

POWER & GROU	POWER & GROUND : 33 pins.					
VDD	-	VCC voltage for ASIC core & CPUs	6			
VDDPLL	-	VCC voltage for DPLL	1			
VDDRTC	-	VCC voltage for RTC split powered	1			
VDDS-MIF	-	VCC voltage dedicated to memory interface	4			
VDDS-RTC	-	VCC voltage dedicated to RTC split powered I/Os	1			
VDDS-1		VCC voltage for ASIC I/Op	2			
VDDS-2	-		1			
VSS	-	common ground for ASIC core, I/Os and CPUs	12			
VSSPLL	-	ground dedicated to DPLL	1			
VSSRTC	-	ground dedicated to RTC split powered	1			
VDDANG	-	Analog VCC for clock squarer.	1			
VSSANG	-	Analog ground for clock squarer	1			
VSSO	-	Reference ground for 32KHz oscillator.	1			



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PAGE: 37/54

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FUNCTIONAL N	NCTIONAL MUXED: 23 pins			Reset
nSCS2	OUT	uWIRE chip select 2.		1
CK16X_IRDA	OUT	IRDA mode: 16X serial transmission clock		0
IO(15:4)	IN/OUT	Additional generic Input/Output.		Input
ADD(22)	OUT	ARM address bus out		0
CLKX_SPI	OUT	SPI Serial clock output		0
SCL	OUT	I2C INTERFACE Master serial clock		Z
SDA	OUT	I2C INTERFACE Serial bidirectional data		Z
LPG	OUT	Light pulse Generator LED control signal		0
PWT	OUT	Pulse Width modulated signal for buzzer		0
PWL	OUT	Pulse Width modulated signal for light		0
ARMCLK	IN	ARM external clock input		Input
nRDYMEM	IN	Ready signal for slow peripheral		
_				
SOFTWARE DE	BUG: 35	oins (test and validation only)	Pull	Reset
XDI_O(7:0)	OUT	DSP XI/O Data bus.		N/A
X_A(4:0)	OUT	DSP XI/O Address bus		N/A
X_IOSTRB	OUT	DSP XI/O strobe		1
TOUT	OUT	DSP timer output.		0
XF	OUT	DSP External flag.		0
INT10n	OUT	DSP external interrupt 10 (DMA int.).		1
INT1n	OUT	DSP external interrupt 1 (RIF transmit int.).		1
INT4n	OUT	DSP external interrupt 4 (MCSI Tx int.).		1
IRQ4	OUT	ARM external interrupt 4 (TPU frame int.).		1
IACKn	OUT	DSP interrupt acknowledge.		1
CLKOUT_DSP	OUT	DSP clock out.		0
DPLLCLK	OUT	DPLL clock out.		0
MCLK	OUT	ARM clock in		0
nOPC	OUT	ARM not op-code fetch		0
nMREQ	OUT	ARM not memory request		0
nWAIT	OUT	ARM not wait		0
MAS(1:0)	OUT	ARM memory access size		10
nFIQ	OUT	ARM fast interrupts.		1
nIRQ	OUT	ARM normal interrupts.		1
nCS6	OUT	ARM chip-select RAM interne		1
TPU_WAIT	OUT	TPU in WAIT mode (WAIT / AT instruction)		0
TPU_IDLE	OUT	TPU in IDLE mode (SLEEP instruction)		1
START BIT		Start hit detection		0

### Table 6: CALYPSO pins description

Note: reset values are defined as follows, 0 : driven low (output) 1 : driven high (output) Z : high impedance (output disabled) N/A : non-applicable

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PAGE: 38/54

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# 9. CALYPSO BALL-OUT

#### 9.1 179GHH PACKAGE

Impor	Important: From Calypso C035 – F751xxx, in table below, replace								
	C11	140		VDD	VSS				
By									
	C11	140		VDD	VSS	nCS4			

Import	Important: From Calypso C035 – F751xxx, in table below, replace								
	K7	63		VDD	VSS	BU	PWT		
	L7	64		VDD	VSS	LT	PWL		
By									
	K7	63		VDD	VSS	BU	PWT/DmaDbg		
	L7	64		VDD	VSS	LT	PWL/nEndDma		

The DmaDbg mode is entered by setting bit 3&4 of ASIC\_CONF\_REG

Ball	Pad	IO supply	Core	Gnd	Functional	Dual mode
B2	1	VDDS-MIF	VDD	VSS	RnW	
C2	2		VDD	VSS	nCS0	
C3	3		VDD	VSS	nCS1	
B1*	4				VSS	
C1	5		VDD	VSS	nCS2	
D3	6		VDD	VSS	nCS3	INT4N
D2	7		VDD	VSS	CS4	ADD(22)
D1	8			•	VDDS-MIF	
F5	9		VDD	VSS	nBHE	IO(14)
E4	10		VDD	VSS	nBLE	IO(15)
E2	11		VDD	VSS	nFOE	X_A(3)
E3	12		VDD	VSS	nFWE	X_A(0)
E1	13				VDD	
F4	14		VDD	VSS	FDP	NIACK
F3	15		VDD	VSS	ADD(0)	
F2	16		VDD	VSS	ADD(1)	
F1	17			•	VSS	
G5	18		VDD	VSS	ADD(2)	
G4	19		VDD	VSS	ADD(3)	
G2	20		VDD	VSS	ADD(4)	
G3	21		VDD	VSS	ADD(5)	
G1	22				VDDS-MIF	
H1	23	1 1	VDD	VSS	ADD(6)	
H3	24		VDD	VSS	ADD(7)	
H2	25	] ]	VDD	VSS	ADD(8)	



# TI- Proprietary Information –

PAGE: 39/54

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HERCROM400G2

Ver 1.4

H4	26		VDD	VSS	ADD(9)	
H5	27		VDD	VSS	ADD(10)	
J1	28		VDD	VSS	ADD(11)	
J2	29		VDD	VSS	ADD(12)	
J3	30		VDD	VSS	ADD(13)	
J4	31		VDD	VSS	ADD(14)	
K1	32				VSS	
K3	33		VDD	VSS	ADD(15)	
K2	34		VDD	VSS	ADD(16)	
K4	35		VDD	VSS	ADD(17)	
J5	36		VDD	VSS	ADD(18)	
L1	37		VDD	VSS	ADD(19)	
L2	38		VDD	VSS	ADD(20)	
L3	39		VDD	VSS	ADD(21)	CK16X_IRDA
M1	40	VDDS-1		VDD		
N1*	41		VDD	VSS	nIBOOT	
M3	42		VDD	VSS	EXT_IRQ	
M2	43		VDD	VSS	IDDQ	
P1*	44		VDD	VSS	EXT_FIQ	
N2	45		VDD	VSS	nRESET_OUT	IO(7)
P2*	46			VSS		
N3	47		VDD	VSS	IO(0)	TPU-WAIT
P3	48		VDD	VSS	IO(1)	TPU-IDLE
L4	49		VDD	VSS	IO(2)	IRQ4
M4	50		VDD	VSS	IO(3)	SIM_RNW
N4	51		VDD	VSS	KBC(0)	NFIQ
P4	52			VSS		
K5	53		VDD	VSS	KBC(1)	NIRQ
L5	54		VDD	VSS	KBC(2)	XDIO(0)
N5	55			VDDS-1		
P5	56		VDD	VSS	KBC(3)	XDIO(1)
M5	57		VDD	VSS	KBC(4)	XDIO(2)
K6	58		VDD	VSS	KBR(0)	XDIO(3)
M6	59		VDD	VSS	KBR(1)	XDIO(4)
P6	60		VDD	VSS	KBR(2)	XDIO(5)
N6	61			VSS	KBR(3)	XDIO(6)
L6	62		VDD	VSS	KBR(4)	
K7	63		VDD	VSS	BO	PWI
	64		VDD	VSS	LI	PVVL
P7	65			VDD		
N7	66		VDD	VSS		
M7	67		VDD	VSS		
M8	68		VUU	VSS	MCUEN(0)	
N8	69			VSS		
P8	70			VSS		IU(8)
L8	/1			VSS	MCUEN(2)	IU(13)
K8	/2			VSS	SDO	IN I 10n
L9	/3			VSS	nSCS0	SCL
N9	74		VDD	VSS	nSCS1	X_A(2)



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### **TI- Proprietary Information –**

PAGE: 40/54

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#### HERCROM400G2

Ver 1.4

P9	75		VDD	VSS	SCLK	INT1n
M9	76		VDD	VSS	SDI	SDA
K9	77		VDD	VSS	MCSI_FSYNCH	IO(12)
M10	78		VDD	VSS	MCSI_RXD	IO(10)
P10	79			VSS		
N10	80		VDD	VSS	MCSI_CLK	IO(11)
L10	81		VDD	VSS	MCSI_TXD	IO(9)
K10	82		VDD	VSS	BDR	
P11	83		VDD	VSS	BCLKR	ARMCLK
N11	84		VDD	VSS	BCLKX	IO(6)
M11	85		VDD	VSS	BDX	
L11	86		VDD	VSS	BFSR	
P12	87		VDD	VSS	BFSX	
N12	88		VDD	VSS	VCLKRX	
P13*	89				VSS	
N13	90		VDD	VSS	VDR	
P14*	91		VDD	VSS	VDX	
M13	92		VDD	VSS	VFSRX	
M12	93		VDD	VSS	TSPACT(0)	
N14*	94				VDD	
M14	95		VDD	VSS	TSPACT(1)	
L12	96		VDD	VSS	TSPACT(2)	
L13	97		VDD	VSS	TSPACT(3)	
L14	98				VDDS-1	
J10	99		VDD	VSS	TSPACT(4)	NREADYMEM
K11	100		VDD	VSS	TSPACT(5)	DPLLCLK
K13	101		VDD	VSS	TSPACT(6)	NCS6
K12	102		VDD	VSS	TSPACT(7)	CLKX_SPI
K14	103	VDDS-1	VDD	VSS	TSPACT(8)	NMREQ
J11	104		VDD	VSS	TSPACT(9)	MAS(1)
J12	105		VDD	VSS	TSPACI(10)	NWALL
J13	106		VDD	VSS	TSPACI(11)	MCLK
J14	107			VSS	TSPCLKX	
H10	108			VSS	TSPDI	10(4)
H11	109			VSS	TSPDU	
H13	110			V55	TSPEN(U)	
HIZ	111			V55	TSPEN(T)	
	112		VDD	V33		
G14 C12	113			Vee		Neceo
G12	114			VSS		N3C32
G13	116			V00		MAS(0)
G10	117			227	SIM RST	
F14	118			VSS	SIM PWRCTRI	10(5)
F13	110			VSS		
F12	120			VSS		START BIT
F11	121		,00			<u>0,7,1,1,</u>
E14	122				VSSPLL	
· ·					·····	



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PAGE: 41/54

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Ver 1.4

E12	123				VSSANG	
E13	124	VDDANG	VDDANG	VSSANG	CLKTCXO	
E11	125				VDDANG	
F10	126		VDDRTC	VSSRTC	ON_OFF	
D14	127				VDDRTC	
D13	128				VDDS-RTC	
D12	129		VDDRTC	VSSRTC	RESPWRONZ	
C14	130				VSSRTC	
B14*	131	VDDO-ICIO	VDDRTC	VSSRTC	IT_WAKEUP	
C12	132		VDDRTC	VSSRTC	CLK32K_OUT	
C13	133		VDDRTC	VSSO	OSC32K_IN	
A14*	134	_		1	VSSO	
B13	135		VDDRTC	VSSO	OSC32K_OUT	
A13*	136	-	VDD	VSS	RFEN	NOPC
B12	137	-		1	VDD	
A12	138	_	VDD	VSS	TCXOEN	
D11	139		VDD	VSS	nBSCAN	
C11	140		VDD	VSS		
B11	141		VDD	VSS	nEMU0	
A11	142				VDDS-2	
E10	143		VDD	VSS	nEMU1	
D10	144		VDD	VSS	TDI	
B10	145		VDD	VSS	тск	
A10	146		VS	S	VSS	
C10	147	VDDS-2	VDD	VSS	TDO	
E9	148		VDD	VSS	TMS	
C9	149		VDD	VSS	CTS_MODEM	XF
A9	150		VDD	VSS	RX_MODEM	
B9	151		VDD	VSS	TX_MODEM	XIOSTRBN
D9	152		VDD	VSS	DSR_MODEM	LPG
E8	153	-	VDD	VSS	RTS_MODEM	TOUT
D8	154		VDD	VSS	RX_IRDA	
A8	155		VDD	VSS	RXIR_IRDA	X_A(1)
B8	156		VDD	VSS	SD_IRDA	CLKOUT_DSP
C8	157		VDD	VSS	TX_IRDA	
C7	158	1	VDD	VSS	TXIR_IRDA	X_A(4)



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**TI- Proprietary Information –** 

PAGE: 42/54

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B7	159		VDD	VSS	DATA(0)
A7	160				VSS
D7	161		VDD	VSS	DATA(1)
E7	162		VDD	VSS	DATA(2)
D6	163		VDD	VSS	DATA(3)
B6	164				VDDS-MIF
A6	165		VDD	VSS	DATA(4)
C6	166		VDD	VSS	DATA(5)
E6	167		VDD	VSS	DATA(6)
C5	168		VDD	VSS	DATA(7)
A5	169	VDDS-MIF			VDD
B5	170		VDD	VSS	DATA(8)
D5	171		VDD	VSS	DATA(9)
E5	172		VDD	VSS	DATA(10)
A4	173				VDDS-MIF
B4	174		VDD	VSS	DATA(11)
C4	175		VDD	VSS	DATA(12)
D4	176		VDD	VSS	DATA(13)
A3	177	]	VDD	VSS	DATA(14)
B3	178		VDD	VSS	DATA(15)
A2*	179				VSS

Table 7: CALYPSO ball mapping



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PAGE: 43/54

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#### PAD I/O BUFFER TYPE 10.

Important: From Calypso C035 – F751xxx, in table below, replace								
C11	140		xxxAVAILABLExx					
011	140	PWR	Х	IDI091				
By	By							
C11	140	PWR	nCS4		OUI831			

PAD Definition				BUFFER TYPE		
Ball	Finger	PAD	PAD_name	Input_Pad	Output_Pad	
B2	1	<b>IO</b>	RnW	IDI041	OUI831	
C2	2	0	nCS0		OUI831	
C3	3	0	nCS1		OUI831	
B1*	4	PWR	VSS	*power*	*power*	
C1	5	0	nCS2		OUI831	
D3	6	IO III	nCS3	IDI041	OUI831	
D2	7	IO III	CS4	IDI041	OUI831	
D1	8	PWR	VDDS-MIF	*power*	*power*	
F5	9	IO III	nBHE	IDI041	OUI831	
E4	10	IO III	nBLE	IDI041	OUI831	
E2	11	0	nFOE		OUI831	
E3	12	IO III	nFWE	IDI041	OUK831	
E1	13	PWR	VDD	*power*	*power*	
F4	14	IO III	FDP	IDI041	OUO431	
F3	15	0	ADD_15_0(0)		OUI831	
F2	16	0	ADD_15_0(1)		OUI831	
F1	17	PWR	VSS	*power*	*power*	
G5	18	0	ADD_15_0(2)		OUI831	
G4	19	0	ADD_15_0(3)		OUI831	
G2	20	0	ADD_15_0(4)		OUI831	
G3	21	0	ADD_15_0(5)		OUI831	
G1	22	PWR	VDDS-MIF	*power*	*power*	
H1	23	0	ADD_15_0(6)		OUI831	
H3	24	0	ADD_15_0(7)		OUI831	
H2	25	0	ADD_15_0(8)		OUI831	
H4	26	0	ADD_15_0(9)		OUI831	
H5	27	0	ADD_15_0(10)		OUI831	
J1	28	0	ADD_15_0(11)		OUI831	
J2	29	0	ADD_15_0(12)		OUI831	
J3	30	0	ADD_15_0(13)		OUI831	
J4	31	0	ADD_15_0(14)		OUI831	
K1	32	PWR	VSS	*power*	*power*	
K3	33	0	ADD_15_0(15)		OUI831	
K2	34	<b>IO</b>	ADD_20_16(16)	IDI041	OUI831	
K4	35	<u>10</u>	ADD_20_16(17)	IDI041	OUI831	



# **TI- Proprietary Information –**

PAGE: 44/54

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15	36		ADD 20 16(18)			
11	37		ADD_20_10(18) ADD_20_16(19)		OU1831	
12	38		ADD 20 16(20)	IDI041	OUI831	
 L3	39	0	ADD 21		OUI831	
M1	40	PWR	VDD	*power*	*power*	
N1*	41	1	nIBOOT	IDI091	ponoi	
M3	42	Í	EXT IRQ	IDI091		
M2	43	ĺ		IDI091		
P1*	44	1	EXT FIQ	IDI091		
N2	45	<mark>IO</mark>	nRESET OUT	IDI041	OUO231	
P2*	46	PWR	VSS	*power*	*power*	
N3	47	<mark>IO</mark>	IO(0)	IDI041	OUO431	
P3	48	<mark>IO</mark>	IO(1)	IDI041	OUO431	
L4	49	<mark>IO</mark>	IO(2)	IDI041	OUO431	
M4	50	<mark>IO</mark>	IO(3)	IDI041	OUO431	
N4	51	<mark>IO</mark>	KBC(0)	IDI041	OUO431	
P4	52	PWR	VSS	*power*	*power*	
K5	53	<mark>IO</mark>	KBC(1)	IDI041	OUO431	
L5	54	<mark>IO</mark>	KBC(2)	IDI041	OUO431	
N5	55	PWR	VDDS-1	*power*	*power*	
P5	56	<mark>IO</mark>	KBC(3)	IDI041	OUO431	
M5	57	<mark>IO</mark>	KBC(4)	IDI041	OUO431	
K6	58	<mark>IO</mark>	KBR(0)	IDI041	OUO231	
M6	59	<mark>IO</mark>	KBR(1)	IDI041	OUO231	
P6	60	<mark>IO</mark>	KBR(2)	IDI041	OUO231	
N6	61	<mark>IO</mark>	KBR(3)	IDI041	OUO231	
L6	62	<mark>IO</mark>	KBR(4)	IDI041	OUO231	
K7	63	0	BU		OUK831	
L7	64	0	LT		OUK431	
P7	65	PWR	VDD	*power*	*power*	
N7	66	1	MCUDI	IDI041		
M7	67	0	MCUDO		OUK431	
M8	68	<mark>IO</mark>	MCUEN(0)	IDI041	OUK431	
N8	69	PWR	VSS	*power*	*power*	
P8	70	<mark>IO</mark>	MCUEN(1)	IDI041	OUK431	
L8	71	<mark>10</mark>	MCUEN(2)	IDI041	OUK431	
K8	72	0	SDO		OUK431	
L9	73	0	nSCS0		OUK431	
N9	74	0	nSCS1		OUK431	
P9	75	0	SCLK		OUI431	
M9	76	<mark>IO</mark>	SDI	IDI041	OUO431	
K9	77	0	MCSI_FSYNCH	IDI041	OUK431	
M10	78	0	MCSI_RXD	IDI041	OUK431	
P10	79	PWR	VSS	*power*	*power*	
N10	80	10	MCSI_CLK	IDI041	OUI431	
L10	81	<u>10</u>	MCSI_TXD	IDI041 OUK431		
K10	82		BDR	IDI041		
P11	83	I	BCLKR	IDI091		
N11	84	<mark>10</mark>	BCLKX	IDI091	OUI431	



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#### **TI- Proprietary Information –**

PAGE: 45/54

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M11	85	0	BDX		OUK431
L11	86	I	BFSR	IDI041	
P12	87	<mark>IO</mark>	BFSX	IDI041	OUK431
N12	88	I	VCLKRX	IDI091	
P13*	89	PWR	VSS	*power*	*power*
N13	90	1	VDR	IDI041	
P14*	91	0	VDX		OUK431
M13	92	I	VFSRX	IDI041	
M12	93	<mark>IO</mark>	TSPACT_4_0(0)	IDI041	OUO231
N14*	94	PWR	VDD	*power*	*power*
M14	95	<mark>IO</mark>	TSPACT_4_0(1)	IDI041	OUO231
L12	96	<mark>IO</mark>	TSPACT_4_0(2)	IDI041	OUO231
L13	97	<mark>10</mark>	TSPACT_4_0(3)	IDI041	OUO231
L14	98	PWR	VDDS-1	*power*	*power*
J10	99	<mark>10</mark>	TSPACT_4_0(4)	IDI041	OUO231
K11	100	0	TSPACT_12_5(5)		OUO231
K13	101	0	TSPACT_12_5(6)		OUO231
K12	102	0	TSPACT_12_5(7)		OUO231
K14	103	0	TSPACT_12_5(8)		OUO231
J11	104	0	TSPACT_12_5(9)		OUO231
J12	105	0	TSPACT_12_5(10)		OUO231
J13	106	0	TSPACT_12_5(11)		OUO431
J14	107	0	TSPCLKX		OUI431
H10	108	0	TSPDI	IDI041	OUK431
H11	109	0	TSPDO	IDI041	OUK431
H13	110	0	TSPEN_0		OUK431
H12	111	10 10	ISPEN_3_1(1)	IDI041	OUK431
H14	112	0	ISPEN_3_1(2)	IDI041	OUK431
G14	113	PWR	VSS	*power*	*power*
G12	114	10 10	ISPEN_3_1(3)	IDI041	OUK431
G13	115	10 10	SIM_IO	IDI041	000431
G11	116		SIM_CD	IDI091	000431
G10	117			IDI041	000431
F14	110			IDI041	000431
F13	119			IDI041	000431
	120			IDI041	001431
	121	PWR		"power"	*power*
E14	122	PWR	VSSPLL	<sup>*</sup> power <sup>*</sup>	*power*
	123	PWR	VSSANG		"power"
	124				*** ***
	120	PVVR			power
	120				*powor*
D14	120			hower.	*power*
D13	120	PVVR			power
	129				*powor*
D14 B1/*	121			power	
C12	122	6			
012	102		OCCOR IN	000474	001431
013	100	<u>  </u>	USU32K_IN	0301/1	



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PAGE: 46/54

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A 4 4 *	404		kana a	<b>.</b>	4 4	
A14*	134	PWR	VSSO	*power*	*power*	
B13	135		OSC32K_OUT	UOS266		
A13*	136	0	RFEN		OUK431	
B12	137	PWR	VDD	*power*	*power*	
A12	138	0	TCXOEN		OUO431	
D11	139	I	NBSCAN	IDI041		
C11	140	PWR	xxxAVAILABLExxx	IDI091		
B11	141	<mark>IO</mark>	nEMU0	IDI091	OUO231	
A11	142	PWR	VDDS-2	*power*	*power*	
E10	143	<mark>IO</mark>	nEMU1	IDI091	OUO231	
D10	144		TDI	IDI091		
B10	145	I	тск	IDI091		
A10	146	PWR	VSS	*power*	*power*	
C10	147	0	TDO		OUK431	
E9	148	1	TMS	IDI091		
C9	149	IO	CTS MODEM	IDI091	OUO231	
A9	150	<mark>10</mark>	RX MODEM	IDI091	OUO231	
B9	151	0	TX MODEM		OUK831	
D9	152	IO	DSR MODEM	IDI091	OUK831	
E8	153	0	RTS MODEM		OUK831	
D8	154	I	RX IRDA	IDI091		
A8	155	IO	RXIR IRDA	IDI091	OUK431	
B8	156	0	SD IRDA		OUK431	
C8	157	0	TX IRDA	IDI041	OUK831	
C7	158		TXIR IRDA	IDI041	OUK831	
B7	159	.0 10	DATA(0)	IDI041	OUI831	
A7	160	PWR	VSS	*power*	*power*	
D7	161				OUI831	
E7	162		DATA(2)	IDI041	OUI831	
D6	163				OUI831	
B6	164	PWR		*power*	*power*	
A6	165					
C6	166				011831	
F6	167				011831	
C5	168				011831	
Δ5	169				*power*	
R5	170					
D5	171				011831	
E5	172		$D\Delta T\Delta(10)$		0111831	
	173				*nower*	
R4	174					
C4	175				011831	
	176		DATA(12)			
Δ4 Λ2	177		DATA(13)			
	170		DATA(14)			
00	1/0					
AZ	179	PWR	VSS	"power^	"power^	

#### Table 8: I/O buffer type in 179 balls version



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PAGE: 47/54

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## 11. APPLICATION EXAMPLE

#### **11.1** Power-supplies connection

#### 11.1.1 Compatibility schematic Nausica CALYPSO



Figure 2: Compatibility connection with Nausica

#### **Restrictions :**

 $\ensuremath{ 1/ \ CALYPSO}$  could be used with NAUSICA without using the CALYPSO split power capability.



2/ It is not possible to use 1.8V external memory on CALYPSO when using a NAUSICA.



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PAGE: 49/54

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#### 11.1.2 IOTA to power split DBB supply connections

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PAGE: 50/54

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#### 11.1.3 Power Supplies connection with IOTA ABB

Figure 3: Power Supplies connection with IOTA ABB



#### 11.2 32KHz quartz connection

See Technical memo 32pcbguide.doc



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PAGE: 52/54

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#### 11.3 SIM card connection

The SIM card or the SIM level-shifters are connected to the chip using:

- SIM\_CLK SIM card reference clock
- SIM\_RST SIM card async/sync reset
- SIM\_IO SIM card bidirectional data line
- SIM\_PWCTRL SIM card power activation
- SIM\_RnW SIM card data line direction
- SIM\_CD SIM card presence detection

The SIM\_RnW signal is only used with some external devices to control level-shifters direction. The SIM\_CD signal should be connected to the SIM card reader in order to get SIM\_CD at low level (GND) when no card is present and at high level (VDDS2) when a card is present. The SIM\_PWCTRL signal can be used for a direct control of the SIM card power-supply. However, this control is S/W programmable through the MCU serial port when using the NAUSICA chip for the SIM card interface.



Figure 4: SIM card connection



#### **Keyboard connection** 11.4

The keyboard is connected to the chip using:

- KBR (4:0) input pins for row lines
- KBC (4:0) output pins for column lines

If a key button of the keyboard matrix is pressed, the corresponding row and column lines are shorted together.

To allow key press detection, all input pins (KBR) are pulled up to VCC and all output pins (KBC) are driving a low level. Any action on a button will generate an interrupt to the microcontroller which will, as answer, scan the column lines with the sequence describe below. This sequence is written to allow detection of simultaneous press actions on several key buttons.

	RESET	IDLE	KEYBOARD SCANNING						
KBC(0)	1	0	1	0	1	1	1	1	0
KBC(1)	1	0	1	1	0	1	1	1	0
KBC(2)	1	0	1	1	1	0	1	1	0
KBC(3)	1	0	1	1	1	1	0	1	0
KBC(4)	1	0	1	1	1	1	1	0	0





#### Figure 5: Keyboard connection



PAGE: 54/54

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